

Absolute Maximum Ratings (@T_A=25°C, unless otherwise specified. Note 1)

Symbol	Parameter	Rating	Unit
V _{CC}	Power Supply Voltage	6	V
T _J	Operation Junction Temperature	150	°C
T _{STG}	Storage Temperature Range	-65 to 150	°C
T _{LEAD}	Lead Temperature (Soldering, 10 seconds)	260	°C
—	ESD (Machine Model)	200	V
—	ESD (Human Body Model)	2000	V

Note 1: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to "Absolute Maximum Ratings" for extended periods may affect device reliability.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage	2.7	5.5	V
T _A	Ambient Operating Temperature Range	-40	85	°C

2.7V Electrical Characteristics (@T_A=25°C, **bold** typeface applies over T_A=-40°C to 85°C, V_{CC}=2.7V, V_{EE}=0V, V_{CM}=1.0V, V_O=V_{CC}/2 and R_L>1MΩ, unless otherwise specified. Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{IO}	Input Offset Voltage	—	—	1.7	7	mV
		—	—	—	9	
I _B	Input Bias Current	—	—	11	250	nA
		—	—	—	500	
I _{IO}	Input Offset Current	—	—	5	50	nA
		—	—	—	150	
V _{CM}	Input Common Mode Voltage Range	for CMRR≥50dB	-0.1	—	1.9	V
I _{CC}	Supply Current	V _O =V _{CC} /2, A _{VCL} =1, No load	—	140	340	μA
			—	—	420	
CMRR	Common Mode Rejection Ratio	0≤V _{CM} ≤1.7V	50	63	—	dB
PSRR	Power Supply Rejection Ratio	2.7V≤V _{CC} ≤5V, V _O =1V	50	60	—	dB
I _{SOURCE}	Output Short Circuit Current	V _O =0V	5	20	—	mA
I _{SINK}		V _O =2.7V	10	30	—	mA
V _{OH}	Output Voltage Swing	R _L =10kΩ to 1.35V	2.60	2.69	—	V
V _{OL}			—	60	180	mV
GBWP	Gain Bandwidth Product	C _L =200pF	—	1	—	MHz
φ _M	Phase Margin	—	—	60	—	deg
G _M	Gain Margin	—	—	10	—	dB

Note 2: Limits over the full temperature are guaranteed by design, but not tested in production.

5V Electrical Characteristics

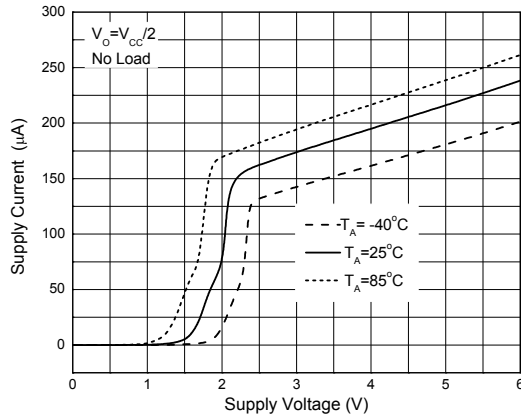
(@T_A=25°C, **bold** typeface applies over T_A=-40°C to 85°C, V_{CC}=5V, V_{EE}=0V, V_{CM}=2.0V, V_O=V_{CC}/2 and R_L>1MΩ, unless otherwise specified. Note 2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{IO}	Input Offset Voltage	—	—	1.7	7	mV
		—	—	—	9	
I _B	Input Bias Current	—	—	15	250	nA
		—	—	—	500	
I _{IO}	Input Offset Current	—	—	5	50	nA
		—	—	—	150	
V _{CM}	Input Common Mode Voltage Range	for CMRR≥50dB	-0.1	—	4.2	V
I _{CC}	Supply Current	V _O =V _{CC} /2, A _{VCL} =1, No load	—	210	440	μA
			—	—	615	
G _V	Large Signal Voltage Gain	R _L =2kΩ	84	100	—	dB
			80	—	—	
CMRR	Common Mode Rejection Ratio	0≤V _{CM} ≤4V	50	63	—	dB
PSRR	Power Supply Rejection Ratio	2.7V≤V _{CC} ≤5V, V _O =1V, V _{CM} =1V	50	60	—	dB
I _{SOURCE}	Output Short Circuit Current	V _O =0V	5	60	—	mA
I _{SINK}		V _O =5V	10	160	—	mA
V _{OH}	Output Voltage Swing	R _L =2kΩ to 2.5V	4.7	4.96	—	V
			4.6	—	—	
		R _L =10kΩ to 2.5V	4.9	4.99	—	
			4.8	—	—	
V _{OL}		R _L =2kΩ to 2.5V	—	120	300	mV
			—	—	400	
		R _L =10kΩ to 2.5V	—	65	180	
			—	—	280	
SR	Slew Rate	—	—	1	—	V/μs
GBWP	Gain Bandwidth Product	C _L =200pF	—	1	—	MHz
ϕ _M	Phase Margin	—	—	60	—	deg
G _M	Gain Margin	—	—	10	—	dB

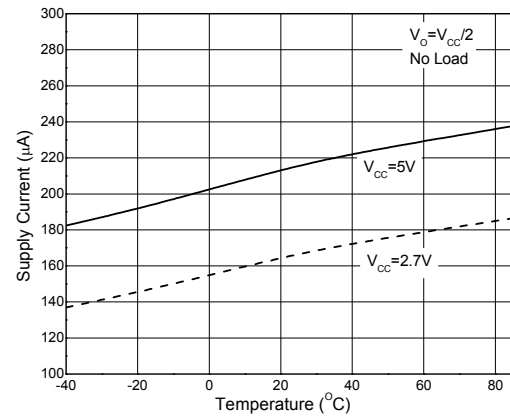
Note 2: Limits over the full temperature are guaranteed by design, but not tested in production.

Performance Characteristics

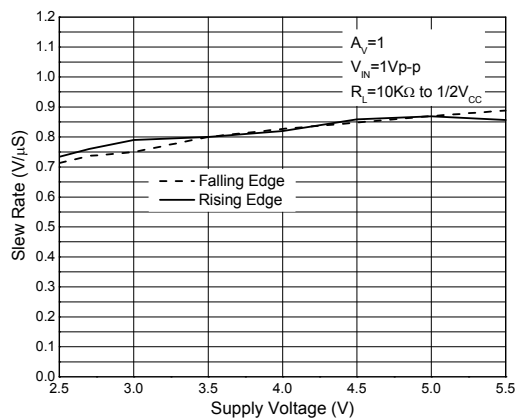
Supply Current vs. Supply Voltage



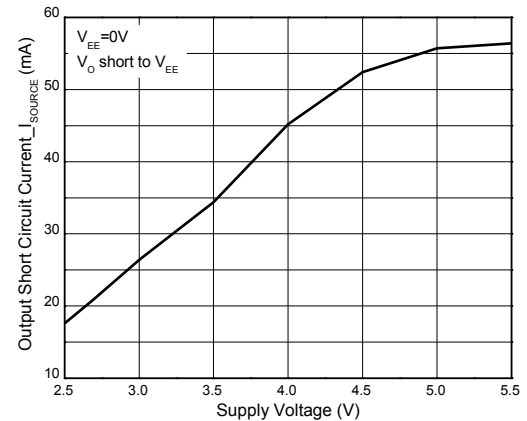
Supply Current vs. Temperature



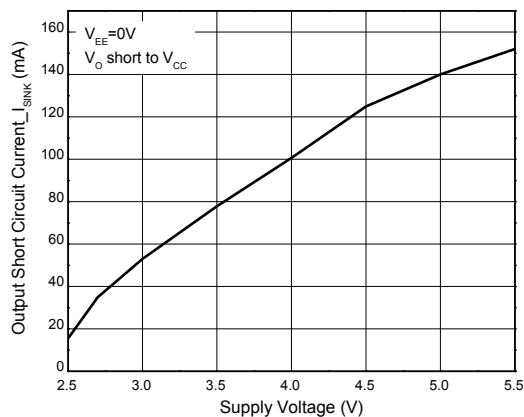
Slew Rate vs. Supply Voltage



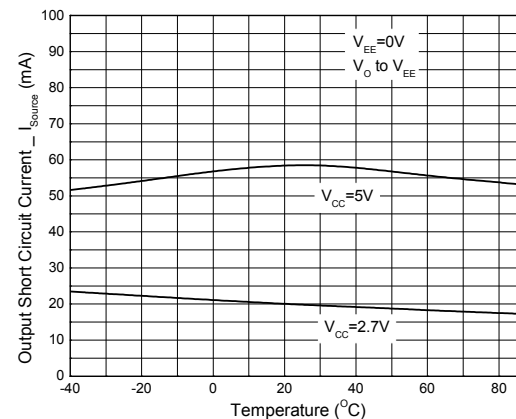
Output Short Circuit Current vs. Supply Voltage



Output Short Circuit Current vs. Supply Voltage

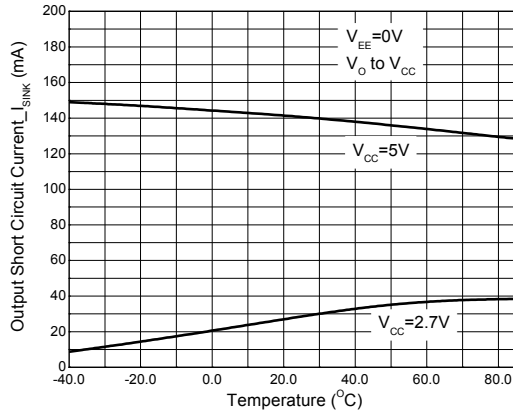


Output Short Circuit Current vs. Temperature

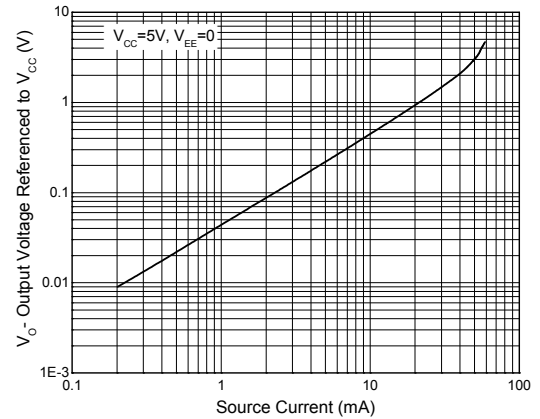


Performance Characteristics (Cont.)

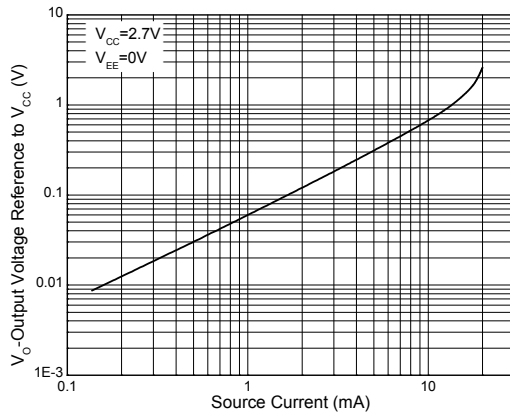
Output Short Circuit Current vs. Temperature



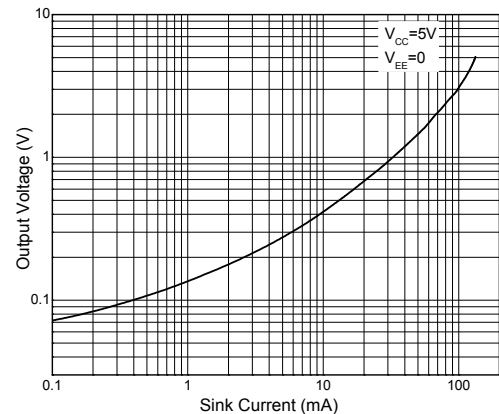
Output Voltage vs. Output Source Current



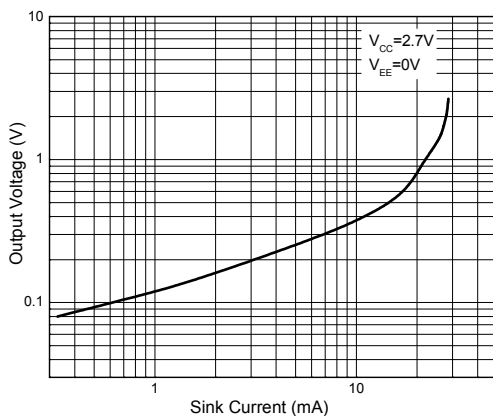
Output Voltage vs. Output Source Current



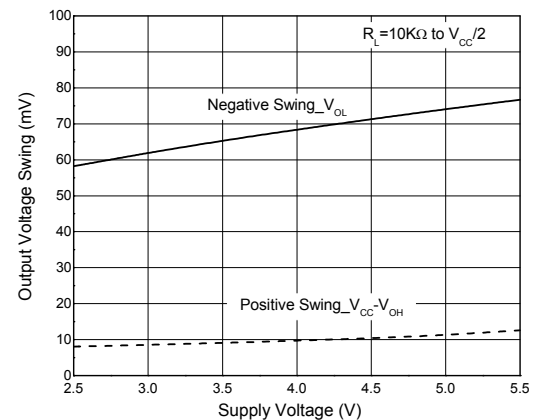
Output Voltage vs. Output Sink Current



Output Voltage vs. Output Sink Current

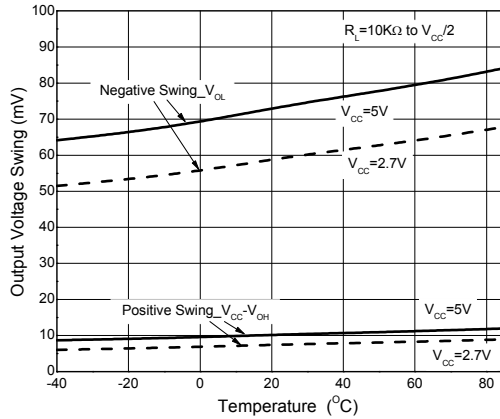


Output Voltage Swing vs. Supply Voltage

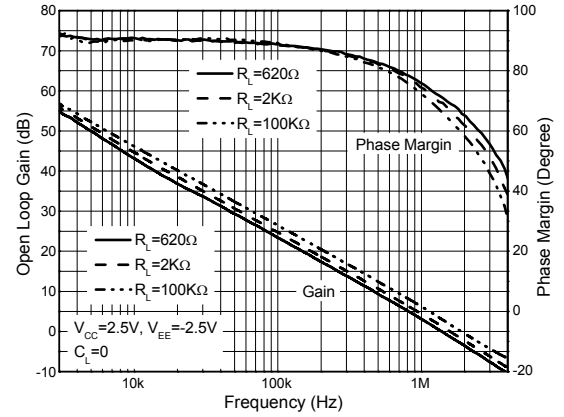


Performance Characteristics (Cont.)

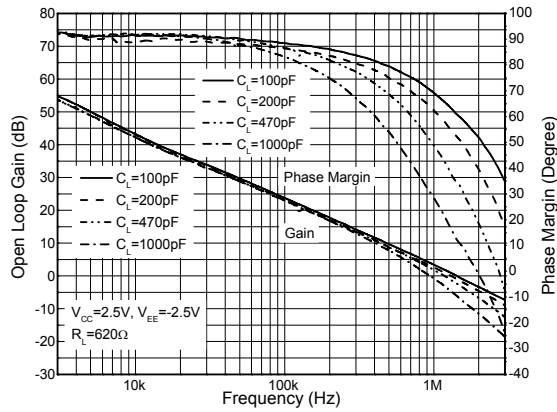
Output Voltage Swing vs. Temperature



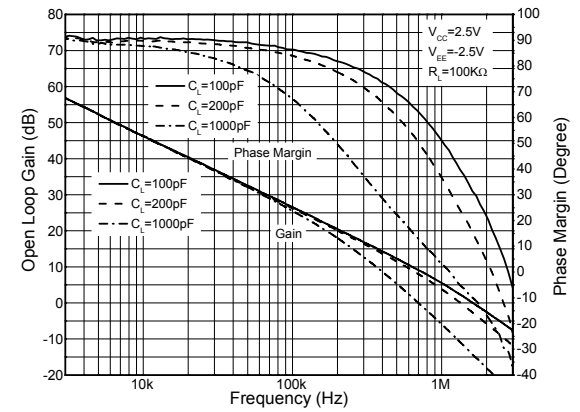
Gain and Phase vs. Frequency and Resistive Load



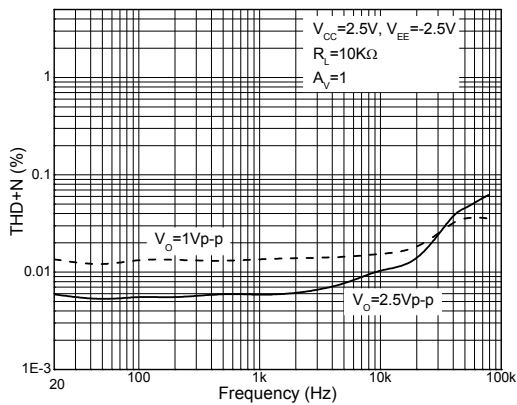
Gain and Phase vs. Frequency and Capacitive Load



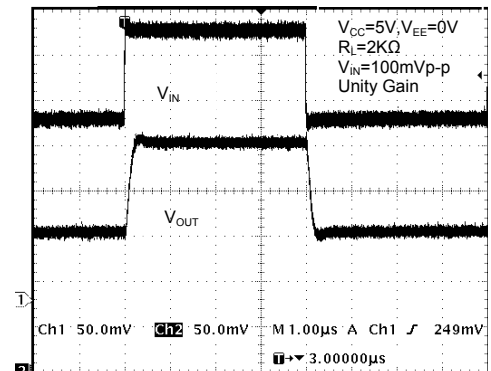
Gain and Phase vs. Frequency and Capacitive Load



THD+N vs. Frequency

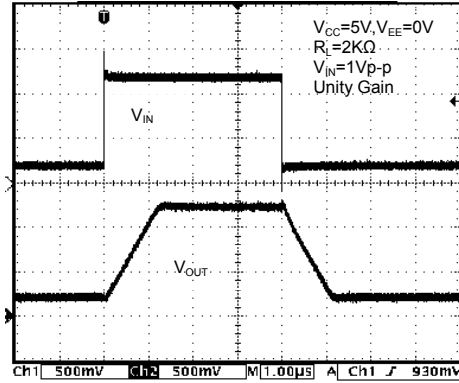


Non-Inverting Input Small Signal Pulse Response

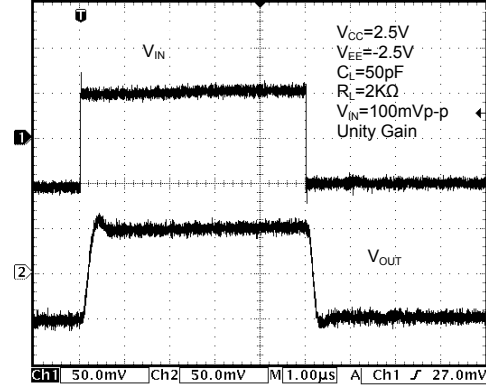


Performance Characteristics (Cont.)

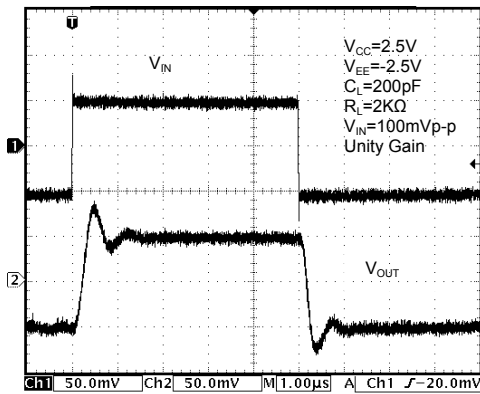
Non-Inverting Input Large Signal Pulse Response



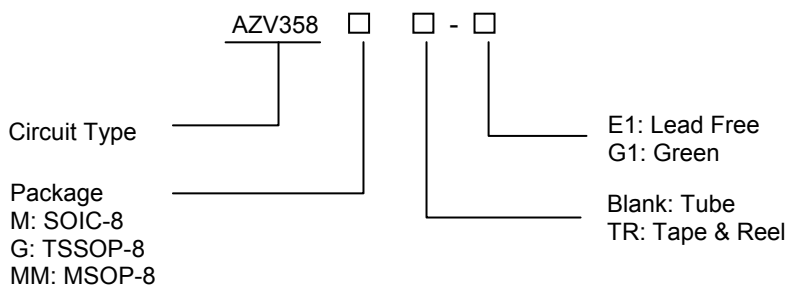
Non-Inverting Input Small Signal Response



Non-Inverting Input Small Signal Response



Ordering Information

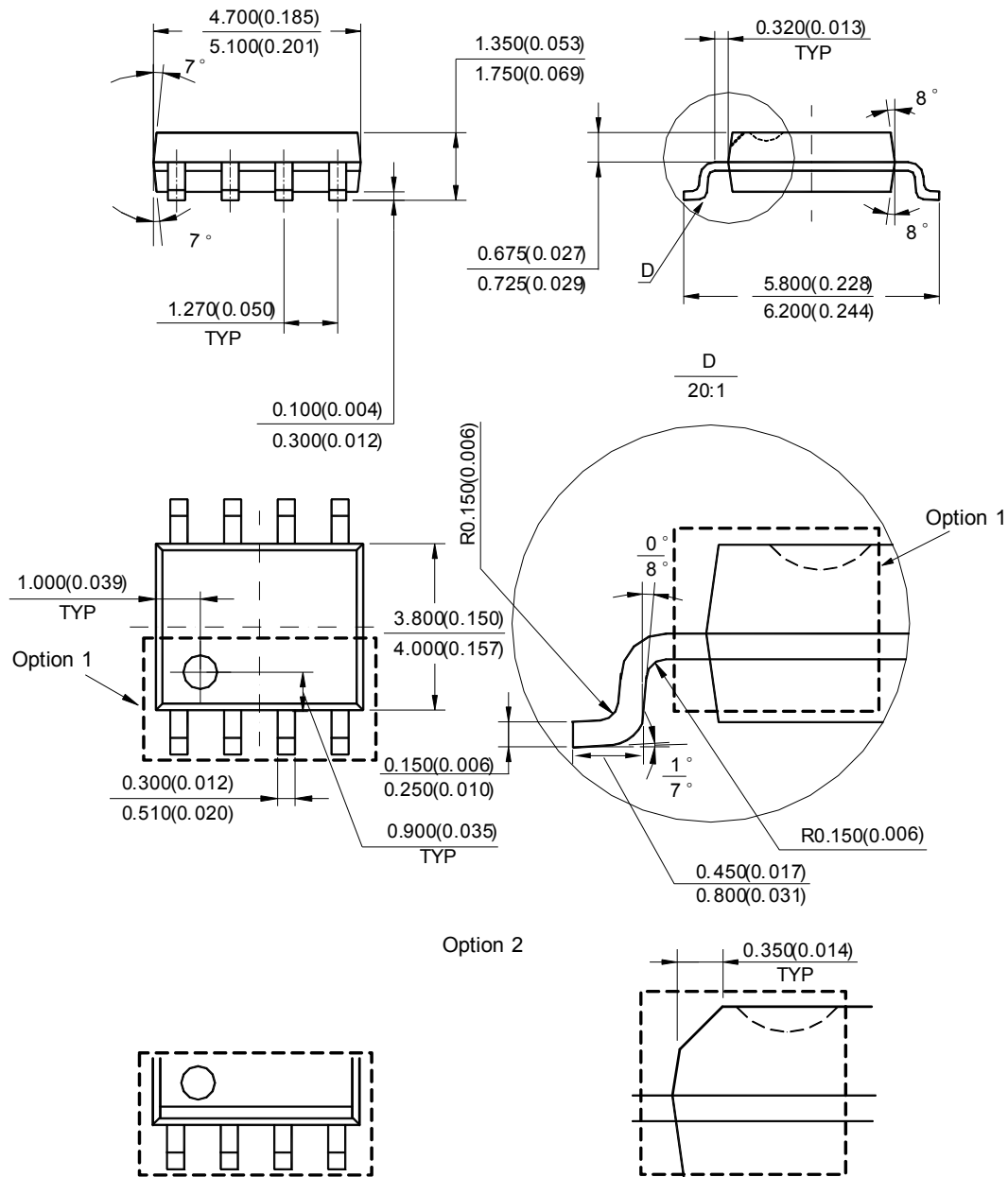


Package	Temperature Range	Part Number		Marking ID		Packing Type
		Lead Free	Green	Lead Free	Green	
SOIC-8	-40 to 85°C	AZV358M-E1	AZV358M-G1	AZV358M-E1	AZV358M-G1	Tube
		AZV358MTR-E1	AZV358MTR-G1	AZV358M-E1	AZV358M-G1	Tape & Reel
TSSOP-8	-40 to 85°C	AZV358G-E1	AZV358G-G1	EG3E	GG3E	Tube
		AZV358GTR-E1	AZV358GTR-G1	EG3E	GG3E	Tape & Reel
MSOP-8	-40 to 85°C	AZV358MM-E1	AZV358MM-G1	AZV358MM-E1	AZV358MM-G1	Tube
		AZV358MMTR-E1	AZV358MMTR-G1	AZV358MM-E1	AZV358MM-G1	Tape & Reel

BCD Semiconductor's Pb-free products, as designated with "E1" suffix in the part number, are RoHS compliant. Products with "G1" suffix are available in green packages.

Package Outline Dimensions (All dimensions in mm(inch).)

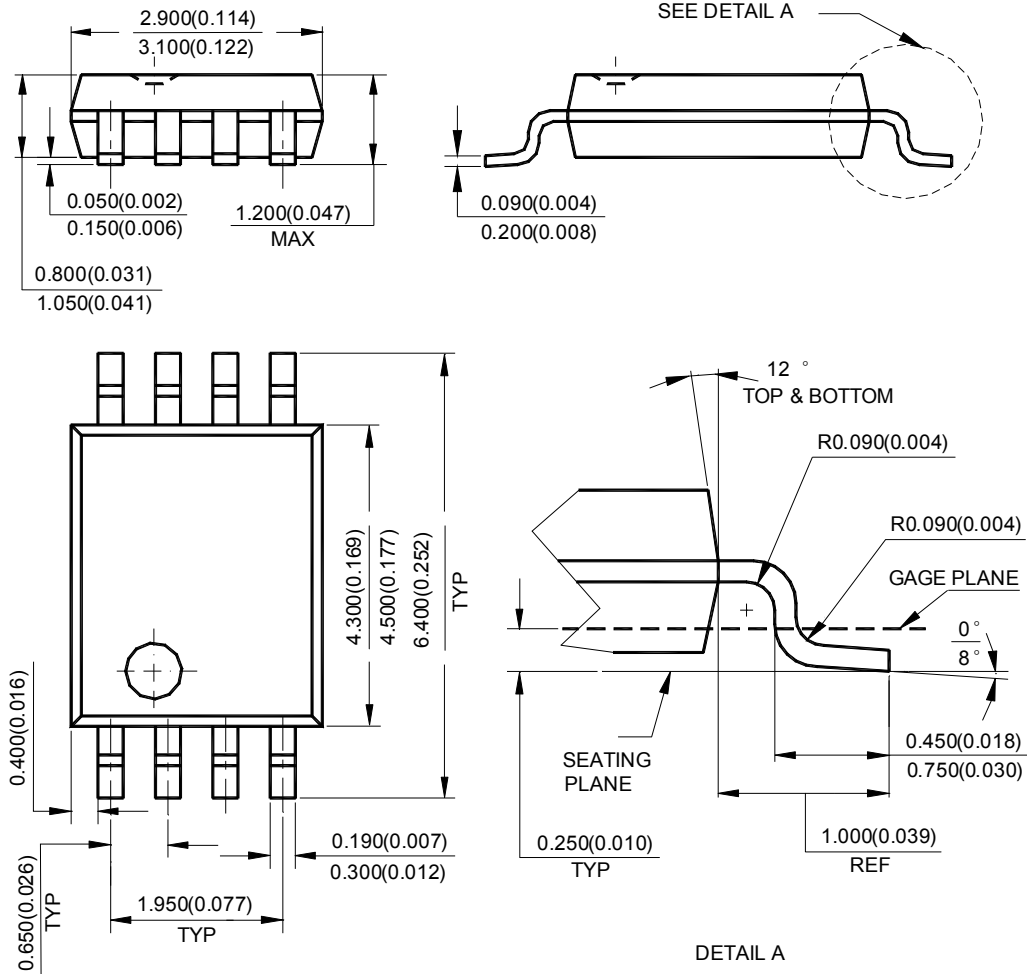
SOIC-8



Note: Eject hole, oriented hole and mold mark is optional.

Package Outline Dimensions (Cont.) (All dimensions in mm(inch).)

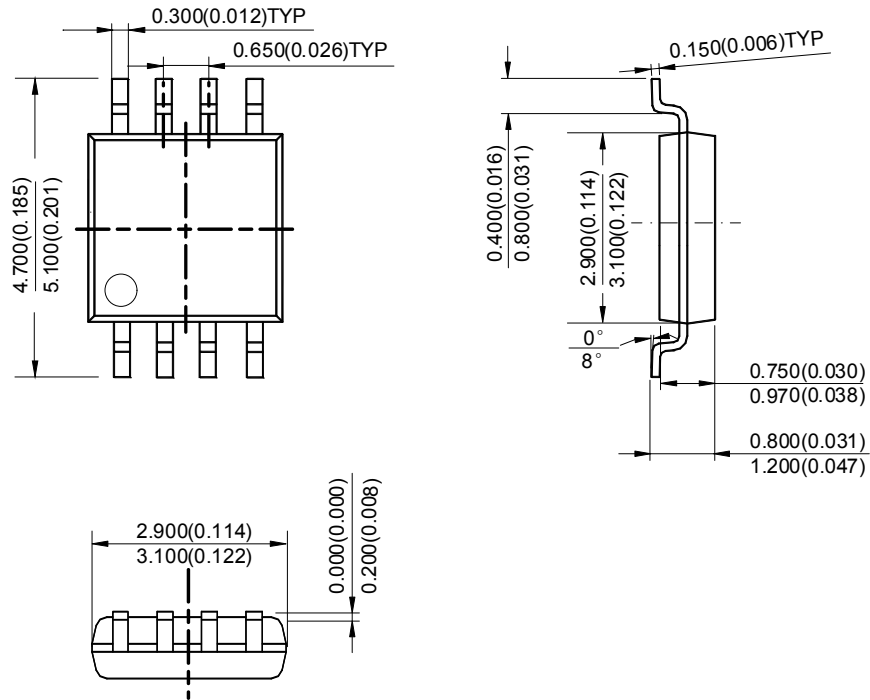
TSSOP-8



Note: Eject hole, oriented hole and mold mark is optional

Package Outline Dimensions (Cont.) (All dimensions in mm(inch).)

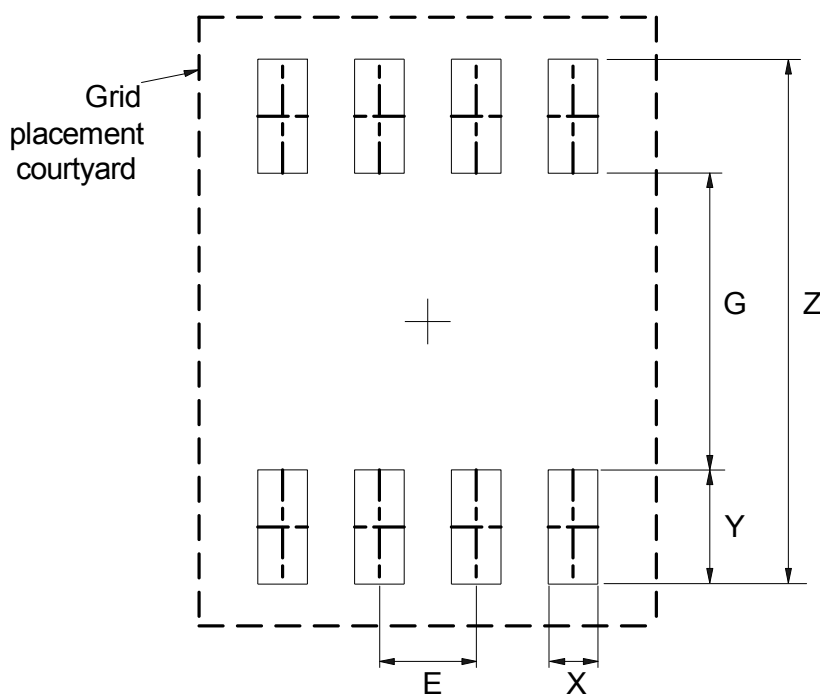
MSOP-8



Note: Eject hole, oriented hole and mold mark is optional

Suggested Pad Layout

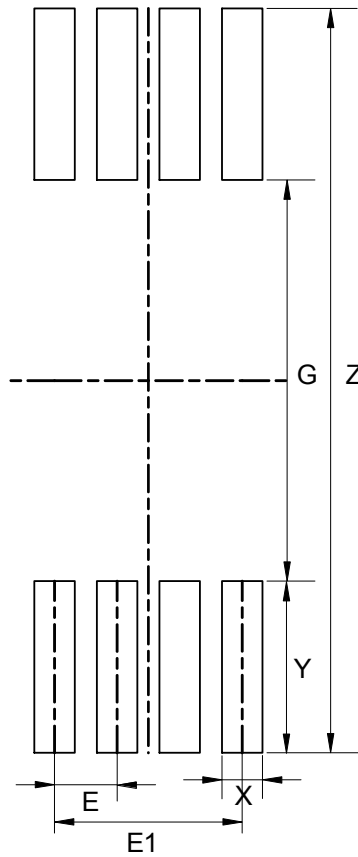
SOIC-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	6.900/0.272	3.900/0.154	0.650/0.026	1.500/0.059	1.270/0.050

Suggested Pad Layout (Cont.)

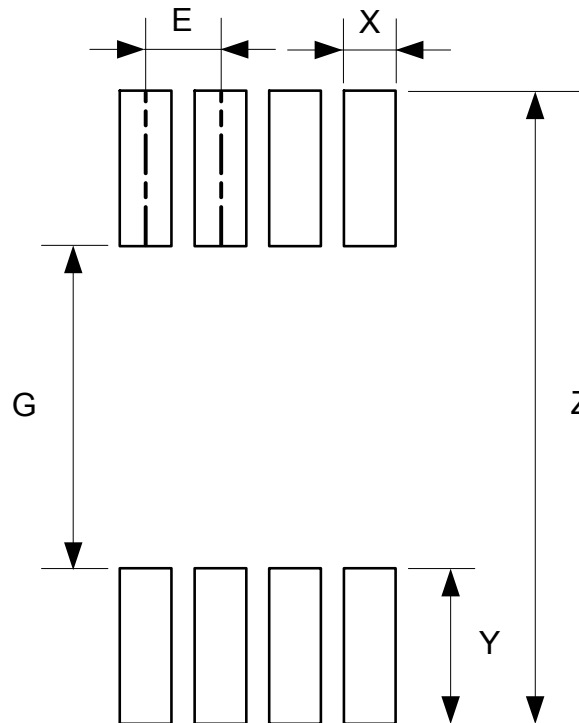
TSSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)	E1 (mm)/(inch)
Value	7.720/0.304	4.160/0.164	0.420/0.017	1.780/0.070	0.650/0.026	1.950/0.077

Suggested Pad Layout (Cont.)

MSOP-8



Dimensions	Z (mm)/(inch)	G (mm)/(inch)	X (mm)/(inch)	Y (mm)/(inch)	E (mm)/(inch)
Value	5.500/0.217	2.800/0.110	0.450/0.018	1.350/0.053	0.650/0.026

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